DATA SHEET

SUNGMUN CODE : NSI-20

DESCRIPTION : SLIDE SWITCH

SUNGMUN ELECTRONICS CO., LTD.

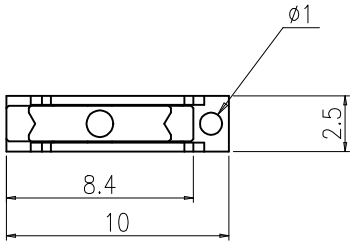
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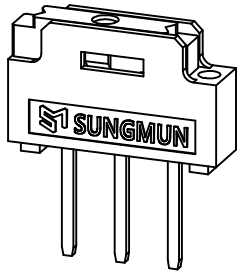
SUNGMUN ELECTRONICS

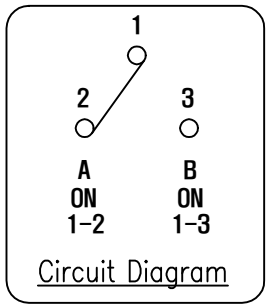
REV NO.	DATE	REVISION	DR	CH	APP
④	22.06.03	CHANGE THE MARKING	K.N KIM	W.J LEE	K.I LEE
⑤	23.10.13	DIN ISO-2768-1m tolerance applied	H.S LEE	K.N KIM	W.J LEE

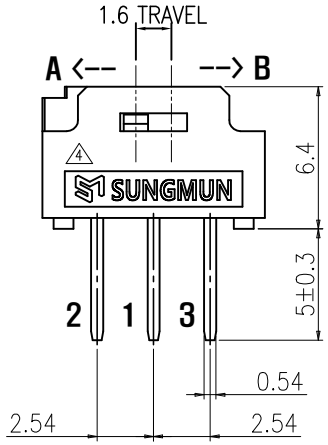
SPECIFICATION

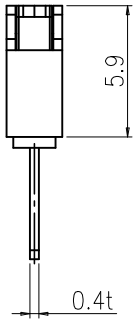
1. Rating : DC12V 0.5A~24V 0.3A.
2. Contact Resistance : 30mΩ Max.
3. Travel : 1.6mm.
4. Operating Force : 250gf ± 150gf.
5. Life Cycle : 2,000 Cycle (with load).
6. Packing : 200pcs Vinyl Bag

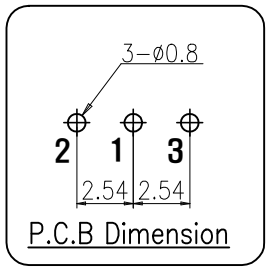














④

BEFORE	AFTER
NSI20KOREA	SUNGMUN

⑤

Din ISO-2768-1m					
Ranges	0.5~3	3~6	6~30	30~120	120~400
Tolerance	±0.1	±0.1	±0.2	±0.3	±0.5

DRAW/DESIGNED	CHECKED	APPROVED	G.TOL	TITLE	MINI SLIDE SWITCH	
J.S YANG	W.J LEE	K.I LEE	±0.3 ⑤			
2021-11-15	2021-11-15	2021-11-15	UNIT: mm / SCALE: 3:1	MODEL NO.	NSI-20	REV.
SUNGMUN ELECTRONICS CO.,LTD			SIZE: A4	DRAW NO.	NSI-20-05	05

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SME 210129

SUNGMUN ELECTRONICS	NSI SERIES SLIDE SWITCH SPECIFICATION	Rev. 02 P : 1 / 2

1. Electrical Characteristics :

1.1 Rating : AC, DC 12V 0.5A~24V 0.3A (Minimum current: 1mA)

1.2 Contact Resistance : Max 30 mΩ

1.3 Insulation Resistance : Min 10,000 MΩ at DC 500V

1.4 Withstanding Voltage : 1min at AC 500V

2. Mechanical Characteristics :

2.1 Operating Force : 250gf ± 150gf

2.2 Travel : 1.6mm

2.3 Insulator :

2.3.1 Case : Glass Fiber resin

2.3.2 Slide : Glass Fiber resin

2.4 Terminal : Nickel, Gold Plate

3. Life Test :

3.1 Test Condition : Operations at a rate of 15-20 cycles in 1 minute

3.1.1 With load : 2,000 cycles

3.1.2 Without load : 10,000 cycles

3.2 Operating Force : With +40%, -40% of Initial Value

3.3 Contact Resistance : Max 200mΩ

4. Environmental Characteristics :

4.1 Operating Temperature : -40℃ to +85℃

4.2 Storage Temperature : -40℃ to +85℃

4.3 Humidity Test :

4.3.1 Test Conditions : Measured 1hour after exposure to ambient
After 96hours exposure at 40±2℃, 90-95% R.H

4.3.2 Insulation Resistance : Min 100MΩ, at DC 500V

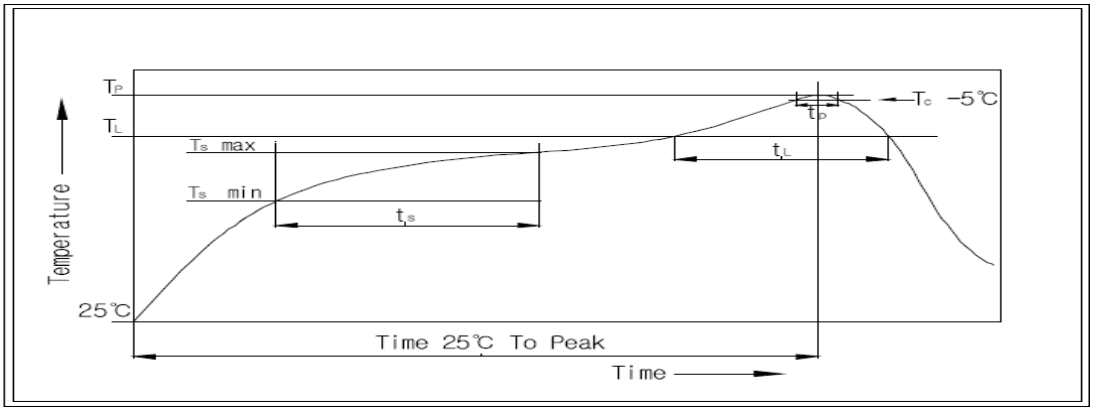
4.3.3 Withstanding Voltage : 1min at AC 250V

5. Solder Conditions :

5.1 Hand Solder : 3~4 sec. at 350℃ (Dipping type)

5.2 Wave Solder : 5 sec. at 260℃ (Dipping type)

5.3 Reflow Solder (SMD type)



5.3.1 Condition for Soldering

Profile Feature	Pb-Free Assembly
Average Ramp-UP Rate(Ts max to TP)	3℃/second max
Preheat - Temperature Min(Ts min) - Temperature Max(Ts max) - Time (ts min to ts max)	 150℃ 200℃ 60-180seconds
Time maintained above: - Temperature (TL) - Time (tL)	 217℃ 60-150seconds
Peak/Classification Temperature(TP)	260℃ +0℃/ -5℃
Time within 5℃ of actual Peak Temperature(TP)	5~10 seconds
Ramp-Down Rate	6℃/sec max
Time 25℃ to Peak Temperature	8 minutes max